WHAT IS CLAIMED IS:

1. A microwave circuit, comprising:

first and second microwave modules, each of which comprises a conductor sandwiched between upper and lower thickfilm dielectrics, and a ground shield surrounding the dielectrics; wherein, at a first end of each of the conductors, the conductor extends from beneath its upper thickfilm dielectric to terminate at a cut edge of its microwave module; the microwave modules being mounted with said cut edges facing one another;

a bridge conductor, electrically coupling the first ends of the conductors; and

a ground shield cap, oriented over the bridge conductor and electrically coupled to the ground shields surrounding the dielectrics.

2. The microwave circuit of claim 1, wherein the bridge conductor comprises a ribbon bond.

3. The microwave circuit of claim 1, wherein the bridge conductor comprises a mesh bond.

4. The microwave circuit of claim 1, wherein the bridge conductor comprises a plurality of wire bonds.

5. The microwave circuit of claim 1, wherein the ground shield cap is electrically coupled to the second ground shields via solder.

6. The microwave circuit of claim 1, wherein the ground shield cap is electrically coupled to the second ground shields via conductive epoxy.

7. The microwave circuit of claim 1, wherein the substrate of each microwave module comprises ceramic.

8. The microwave circuit of claim 1, wherein the first and second dielectrics of each microwave module comprise a KQ dielectric.

9. A microwave circuit, comprising:

first and second microwave modules, each comprising i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from an end of the conductor terminating at or near a cut edge of the microwave module; the microwave modules being mounted with said cut edges facing one another;

a bridge conductor, electrically coupling said ends of the conductors of the microwave modules; and

a ground shield cap, oriented over the bridge conductor and electrically coupled to the second ground shields of the microwave modules.

10. A method for coupling first and second microwave modules, wherein each microwave module comprises i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; and wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from a first end of the conductor; the method comprising:

for each of the microwave modules, cutting the microwave module in proximity to the first end of the conductor, thereby defining a first edge of the microwave module;

mounting the microwave modules adjacent one another, with their first edges facing each other;

electrically coupling said first ends of the conductors of the microwave modules; and

placing a ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground shields of the microwave modules.

11. The method of claim 10 wherein the conductors are electrically coupled using a ribbon bond.

12. The method of claim 10, wherein the conductors are electrically coupled using a mesh bond.

13. The method of claim 10, wherein the conductors are electrically coupled using a plurality of wire bonds.

14. The method of claim 10, wherein the ground shield cap is electrically coupled to the second ground shields via solder.

15. The method of claim 10, wherein the ground shield cap is electrically coupled to the second ground shields via conductive epoxy.

16. A method, comprising:

selecting first and second microwave modules, each comprising i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from an end of the conductor terminating at or near a cut edge of the microwave module;

mounting the microwave modules adjacent one another, with said cut edge of the first microwave module facing said cut edge of the second microwave module;

electrically coupling said ends of the conductors of the microwave modules; and

placing a ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground shields of the microwave modules.

17. The method of claim 16, wherein the conductors are electrically coupled using a ribbon bond.

18. The method of claim 16, wherein the conductors are electrically coupled using a mesh bond.

19. The method of claim 16, wherein the conductors are electrically coupled using a plurality of wire bonds.

20. The method of claim 16, wherein the ground shield cap is electrically coupled to the second ground shields via solder.

21. The method of claim 16, wherein the ground shield cap is electrically coupled to the second ground shields via conductive epoxy.